

L Number	Hits	Search Text	DB	Time stamp
1	55	(sin with (etch near rate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:15
2	22	((sin and (silicon or wafer)) with (etch near rate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:21
3	139	((sin and (silicon or wafer)) with (cmp or polish))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:41
4	31	((sin and (silicon or wafer)) with (cmp or polish))) and (sin with stop)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:36
5	22	((sin and (silicon or wafer)) with (cmp or polish))) and (sin with stop)) and (@ad<20010501)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:51
6	1	("4954875").PN.	USPAT	2003/11/29 16:38
7	0	((sin and (silicon or wafer)) with (cmp or polish))) and (sin with stop)) and (@ad<20010501)) and (wafer00 with (cmp or polish))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:41
8	5	((sin and (silicon or wafer)) with (cmp or polish))) and (sin with stop)) and (@ad<20010501)) and (wafer with (cmp or polish))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:49
9	1	("5721173").PN.	USPAT	2003/11/29 16:47
10	1	("5712205").PN.	USPAT	2003/11/29 16:48
11	1	("5444857").PN.	USPAT	2003/11/29 16:48
12	13157	(sin or nitride)and (wafer with (cmp or polish or thin or remove or removal or thinning))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:50
13	51383	(wafer with (cmp or polish or thin or remove or removal or thinning))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:50
14	1941	((wafer with (cmp or polish or thin or remove or removal or thinning))) and ((sin or nitride) with (wafer with (cmp or polish or thin or remove or removal or thinning)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:51
15	1505	((wafer with (cmp or polish or thin or remove or removal or thinning))) and ((sin or nitride) with (wafer with (cmp or polish or thin or remove or removal or thinning)))) and (@ad<20010501)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/11/29 16:53